







IFN5197, IFN5198, IFN5199 Dual Matched N-Channel JFET

Features

- InterFET <u>N0016H Geometry</u>
 Low Leakage: 10 pA Typical
- Low Input Capacitance: 3.5 pF Typical
- · High Input Impedance
- Replacement for IFN5197,8,9
- RoHS Compliant
- SMT, TH, and Bare Die Package options.

Applications

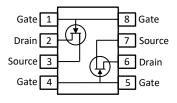
- · Low Noise Differential Amplifier
- · Differential Amplifier
- JFET Input Op-Amps

Description

The -50V InterFET IFN5197, IFN5198, and IFN5199 JFET's are targeted for low noise differential amplifier designs. Gate leakages are less than 10pA at room temperatures. The TO-71 package is hermetically sealed and suitable for military applications. Custom specifications, matching, and packaging options are available.

Gate Source TO-71 Bottom View Source TO-71 Bottom View Source TO-71 Bottom View

SOIC8 Top View





Product Summary

	Parameters	IFN5197 Min	IFN5198 Min	IFN5199 Min	Unit
BV _{GSS}	Gate to Source Breakdown Voltage	-50	-50	-50	V
I _{DSS}	Drain to Source Saturation Current	0.7	0.7	0.7	mA
$V_{GS(off)}$	Gate to Source Cutoff Voltage	-0.7	-0.7	-0.7	V
GFS	Forward Transconductance	0.7	0.7	0.7	mS

Ordering Information Custom Part and Binning Options Available

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Part Number	Description	Case	Packaging			
IFN5197; IFN5198; IFN5199	Through-Hole	TO-71	Bulk			
SMP5197; SMP5198; SMP5199	Surface Mount	SOIC8	Bulk			
	7" Tape and Reel: Max 500 Pieces		Minimum 500 Pieces			
SMP5197; SMP5198; SMP5199	13" Tape and Reel: Max 2,500 Pieces	SOIC8	Tape and Reel			
IFN5197COT; IFN5198COT;						
IFN5199COT *	Chip Orientated Tray (COT Waffle Pack)	СОТ	70/Waffle Pack			
IFN5197CFT; IFN5198CFT;						
IFN5199CFT *	Chip Face-up Tray (CFT Waffle Pack)	CFT	70/Waffle Pack			

^{*} Bare die packaged options are designed for matched specifications but not 100% tested



Disclaimer: It is the Buyers responsibility for designing, validating and testing the end application under all field use cases and extreme use conditions. Guaranteeing the application meets required standards, regulatory compliance, and all safety and security requirements is the responsibility of the Buyer. These resources are subject to change without notice.









Electrical Characteristics

Maximum Ratings (@ T_A = 25°C, Unless otherwise specified)

	Parameters	Value	Unit
V_{RGS}	Reverse Gate Source and Gate Drain Voltage	-50	V
I _{FG}	Continuous Forward Gate Current	50	mA
PD	Continuous Device Power Dissipation	250	mW
Р	Power Derating	4.3	mW/°C
Τı	Operating Junction Temperature	-55 to 125	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Static Characteristics (@ TA = 25°C, Unless otherwise specified)

			IFN5197, IFN5198, IFN5199			
	Parameters	Conditions	Min	Тур	Max	Unit
V _{(BR)GSS}	Gate to Source Breakdown Voltage	$I_G = -1\mu A$, $V_{DS} = 0V$	-50			V
I _{GSS}	Gate to Source Reverse Current	$V_{GS} = -30V$, $V_{DS} = 0V$, $T_A = 25$ °C $V_{GS} = -30V$, $V_{DS} = 0V$, $T_A = 150$ °C			-25 -50	pA nA
IG	Gate Operating Current	V_{DS} = 20V, I_D = 200 μ A, T_A = 25°C V_{DS} = 20V, I_D = 200 μ A, T_A = 125°C			-15 -15	pA nA
V _{GS(OFF)}	Gate to Source Cutoff Voltage	$V_{DS} = 20V$, $I_D = 1nA$	-0.7		-4.0	V
V _{GS}	Gate Source Voltage	$V_{DS} = 20V$, $I_D = 200\mu A$	-0.2		-3.8	٧
I _{DSS}	Drain to Source Saturation Current	$V_{DS} = 20V$, $V_{GS} = 0V$ (Pulsed)	0.7		7	mA

Dynamic Characteristics (@ TA = 25°C, Unless otherwise specified)

		IFN5197, IFN5198, IFN5199					
Parameters		Conditions		Min	Тур	Max	Unit
G _{FS}	Forward Transconductance	$V_{DS} = 20V, V_{GS} = 0V, f$ $V_{DS} = 20V, I_D = 200\mu A, f$		1 0.7		4 1.6	mS
Gos	Output Conductance	$V_{DS} = 20V$, $V_{GS} = 0V$, $f = V_{DS} = 20V$, $I_D = 200\mu A$, $f = 200\mu A$				50 4	μS
C _{iss}	Input Capacitance	$V_{DS} = 20V, V_{GS} = 0V, f =$: 1MHz			6	pF
Crss	Reverse Capacitance	V _{DS} = 20V, V _{GS} = 0V, f =	: 1MHz			2	pF
e _n	Equivalent Circuit Input Noise Voltage	V _{DS} = 20V, I _D = 200μA, f	= 1kHz			20	nV/√Hz
V _{GS1} – V _{GS2}	Differential Gate Source Voltage	V _{DS} = 20V, I _D = -200μA	IFN5197 IFN5198 IFN5199			5 10 15	mV
$\frac{\left V_{GS1}-V_{GS2}\right }{\Delta T}$	Differential Gate Source Voltage with Temperature	V _{DS} = 20V, I _D = 200μA T _A = 25°C, T _B = 125°C	IFN5197 IFN5198 IFN5199			1 2.5 4	mV/°C



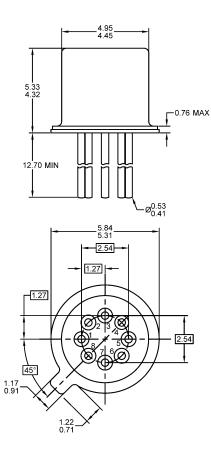






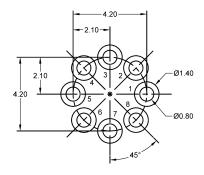
TO-71 Mechanical and Layout Data

Package Outline Data



- 1. All linear dimensions are in millimeters.
- Eight leaded device. Not all leads are shown in drawing views.
- 3. Some package configurations will not populate pin 8 and/or pin 4.
- 4. Package weight approximately 0.35 grams
- Bulk product is shipped in standard ESD shipping material
- 6. Refer to JEDEC standards for additional information.

Suggested Bent Lead Through-Hole Layout



- 1. All linear dimensions are in millimeters.
- Pads 8 and/or pad 4 can be eliminated for devices with less pins.
- The suggested land pattern dimensions have been provided as an eight pin bent lead reference only. A more robust pattern may be desired for wave soldering or reduced pin count.



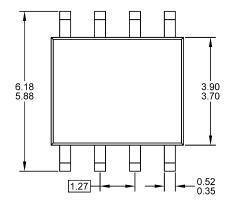


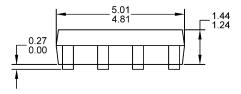


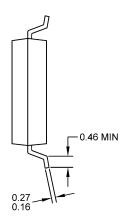


SOIC8 Mechanical and Layout Data

Package Outline Data

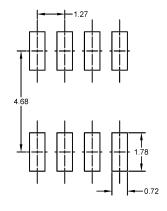






- 1. All linear dimensions are in millimeters.
- 2. Package weight approximately 0.21 grams
- 3. Molded plastic case UL 94V-0 rated
- For Tape and Reel specifications refer to InterFET CTC-021 Tape and Reel Specification, Document number: IF39002
- Bulk product is shipped in standard ESD shipping material
- 6. Refer to JEDEC standards for additional information.

Suggested Pad Layout



- 1. All linear dimensions are in millimeters.
- The suggested land pattern dimensions have been provided for reference only. A more robust pattern may be desired for wave soldering.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

InterFET:

IFN5196 IFN5197 IFN5198 IFN5199